



Product Change Notification

Change Notification #: 115088-00
Change Title: Intel® Server System R2308WTTYSR, PCN115088-00, Product Design, Hot Swap Back Plane Sheet Metal Locator Tab Modification

Date of Publication: November 15, 2016

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

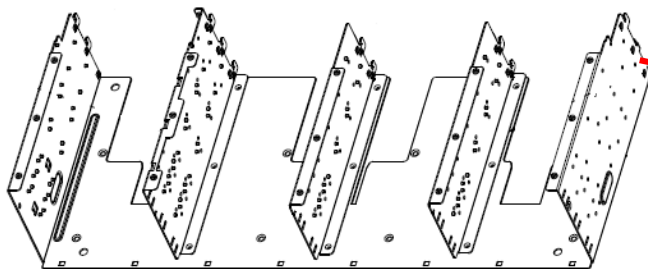
Date Customer Must be Ready to Receive Post-Conversion Material: *	November 30, 2016
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** Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.*

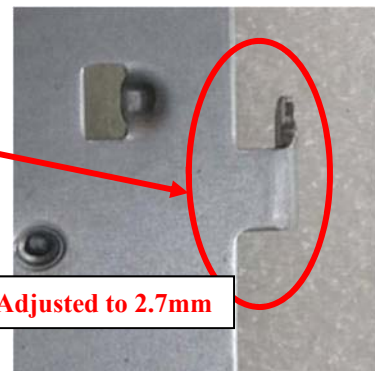
Description of Change to the Customer:

Intel is implementing the following changes on the Intel® Server Systems R2308WTTYSR:

1. The sheet metal of the locator at the bottom tab of the hot swap back plane (HSBP) in the right side will be modified to ensure gap of 2.7mm. This modification is needed to provide reliable engagement between the drive and the backplane connectors. Please see additional information in the TA-1107 available at: <http://www.intel.com/content/www/us/en/support/server-products/000022064.html?wapkw=ta-1107>.



Drives Cage



HSBP Locator tab

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications. For that reason Intel recommends that the customer perform a standard level of evaluation.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
R2308WTTYSR	943829	J11493-005	J11493-006

PCN Revision History:

Date of Revision:

November 15, 2016

Revision Number:

00

Reason:

Originally Published PCN



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115088-00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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